

**ABSTRACT OF THE DISCLOSURE**

A method is provided for forming a wafer stack. This may include providing a first wafer having a first plurality of metalized trenches on a surface of the first wafer. A second wafer may be provided having a second plurality of metalized trenches on a surface of the second wafer facing the first wafer. The first plurality of metalized trenches may be solder bonded to the second plurality of metalized trenches.